



*Institute of Electrical Engineering
Slovak Academy of Sciences, Bratislava
Slovak republic*

Performance of semi-insulating GaAs-based radiation detectors: Role of key physical parameters of base material

8TH INTERNATIONAL
WORKSHOP ON
RADIATION
IMAGING
DETECTORS

2 - 6 July 2006
PISA, ITALY

International Workshop on
8th
iWoRiD
Radiation Imaging Detectors

F. Dubecký

IEE SAS, Bratislava, Slovakia

V. Nečas

IEEIT SIT, Bratislava, Slovakia

C. Ferrari

IMEM – C.N.R., Parma, Italy

OUTLINE

- **MOTIVATION**
- **RADIATION DETECTOR CHARACTERISTICS**
 - Key detector-grade material aspects
- **APPLICATIONS**
 - Monolithic LEC SI **GaAs** strip line in edge-on configuration
 - Line concept of SI **GaAs** chip
 - First “quantum” X-ray images
 - “Quantum” X-CT: preliminary
- **GaAs MATERIAL FOR RADIATION DETECTORS**
 - Key material characteristics
 - Characteristics summary
 - Performances of fabricated detectors
- **CONCLUSIONS**

Motivation I: New applications of semiconductor monolithic array detectors in X- and gamma-ray detection

NEW DETECTOR APPLICATIONS

- **BASIC KNOWLEDGE:** *Experiments in physics
X-ray astronomy....
¹¹⁵InP: Solar neutrino astrophysics*
- **MEDICINE** *Digital X-ray radiology (stomatology,
mammography), XCT
Positron emission tomography*
- **NONDESTRUCTIVE ON-LINE CONTROL** *Material
defect and process control*
 - **SECURITY**
*Contraband inspections: cargo control
Detection of drugs and plastic explosives
Cultural heritage's study*
 - **MONITORING**
*Environmental control and radioactive waste
management
Metrology (testing of radioactive sources,
spectrometry...)*

IMPROVEMENTS IN X-RAY DIGITAL RADIOLOGY USING SEMICONDUCTOR DETECTORS

- **LOWER DOSE TO PATIENT**
- **MUCH BETTER RESOLUTION IN CONTRAST**
(more than 2 orders of magnitude)
- **DETERMINATION OF THE OBJECT DENSITY**
(Dual X-ray or "colour" imaging technique)
- **3-D IMAGE POSSIBLE USING CT METHOD**
 - **NO POLLUTION DUE TO CHEMICAL
PROCESSING**
(Necessary in the case of film application)
- **SIMPLE AND SPACE SAVING STORAGE OF
DIGITAL DATA**
- **ON-LINE PROCESS CONTROL & DIAGNOSTICS**
OTHERS...???

„COLOUR IMAGING“ in digital radiography

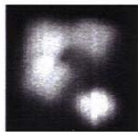
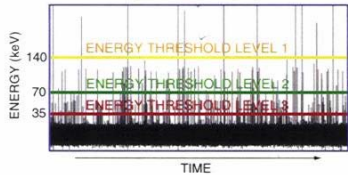
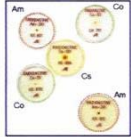
Application 1: Simultaneous measurement of images at different energy regions

– Energy-differentiated RI* images –

Images were measured by linear scanning over radioisotopes (RI) with the radiation line sensor.
Energy-differentiated imaging allows color visualization and identification of different radioisotopes.
Images from different radioisotopes can be visualized by energy discrimination for easy color identification.

* RI: radioisotope

Radioisotope arrangement



Images obtained without energy differentiation: shows only the radiation intensity distribution

Energy-differentiated images

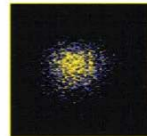


Image obtained with ¹³⁷Cs only (Energy: 140 keV or higher)

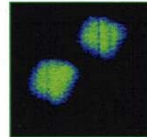


Image obtained with ⁵⁷Co only (Energy: 70 keV to 140 keV)

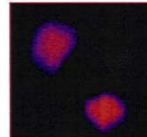
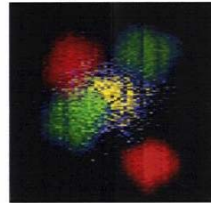


Image obtained with ²⁴¹Am only (Energy: 35 keV to 70 keV)

Composite image with energy-differentiation



Easy identification of radioisotopes

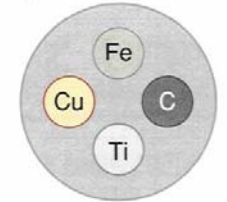
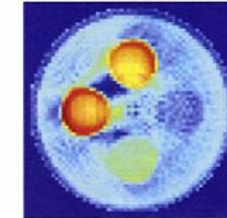
Application 3: Eliminating effect from beam scattering and hardening

Images obtained without energy differentiation are subject to effects from scattered rays and beam hardening. These scattered rays and beam hardening can be eliminated by setting the proper energy differentiation levels.

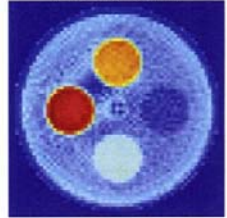
● Sample of aluminum cylinder with a copper, iron, titanium and carbon rods inserted inside the cylinder



Image obtained without energy differentiation (20 keV to 150 keV)



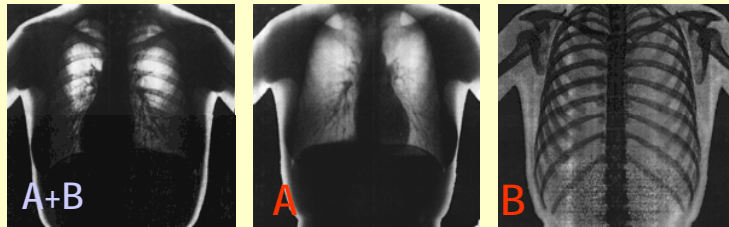
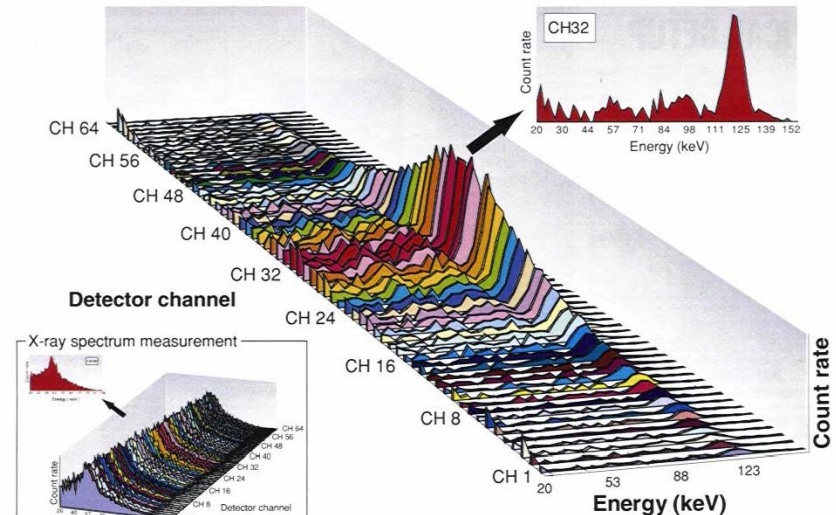
Energy-differentiated image (90 keV or higher)



Application 4: Gamma-ray and X-ray spectrum measurement

Highly detailed spectrum measurements can be made by auto sweep of the comparator levels.

● ⁵⁷Co spectrum measurement



A, B: Dual energy digital radiographs

MOTIVATION II

SI **GaAs** MATERIAL PROPERTIES

- ✓ Radiation hard
- ✓ **Low cost**
- ✓ Fast
- ✓ Wide band gap allows operation at RT
- ✓ *Highly developed technology processing*
- ✓ **Easily commercially available**
- ✓ **Bulk material – no limitation in thickness**
- ✓ **HIGH QUALITY!!**

LINE (2D) SCANNING TECHNIQUE IN RADIOGRAPHIC IMAGING

Quantum XCT

- ✓ Technical **simplest** imaging solution
- ✓ **Lowest cost**
- ✓ Useful for fast testing of detector applicability in X-ray imaging
- ✓ **High quality of X-ray image (good scattered photons rejection)**
- ✓ *Useful in many industrial, medical and security applications*
- ✓ Applicable in basic and space research

Key semiconductor material and detector characteristics

REQUIREMENTS TO SEMICONDUCTOR DETECTOR-GRADE MATERIAL

$$Z > 30; E_G > 1.3 \text{ eV}, \tau, \rho \text{ (RT), high } v_d, \mu_d$$

high homogeneity, low density of structural, space-charge and point defects, fast reaction

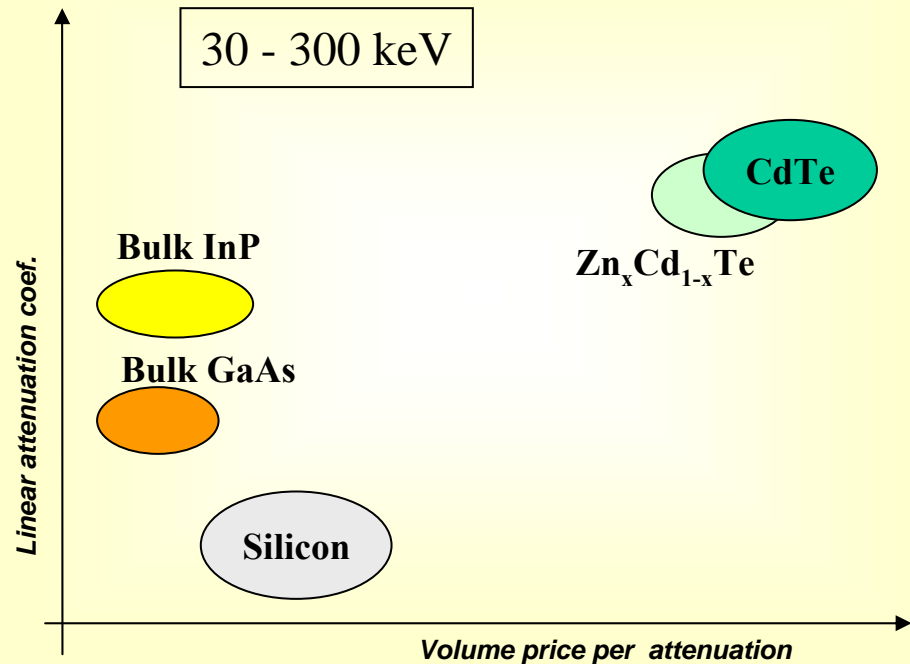
LOW COST

CANDIDATE SEMICONDUCTORS

II-VI: CdTe, CdZnTe, HgI₂,...

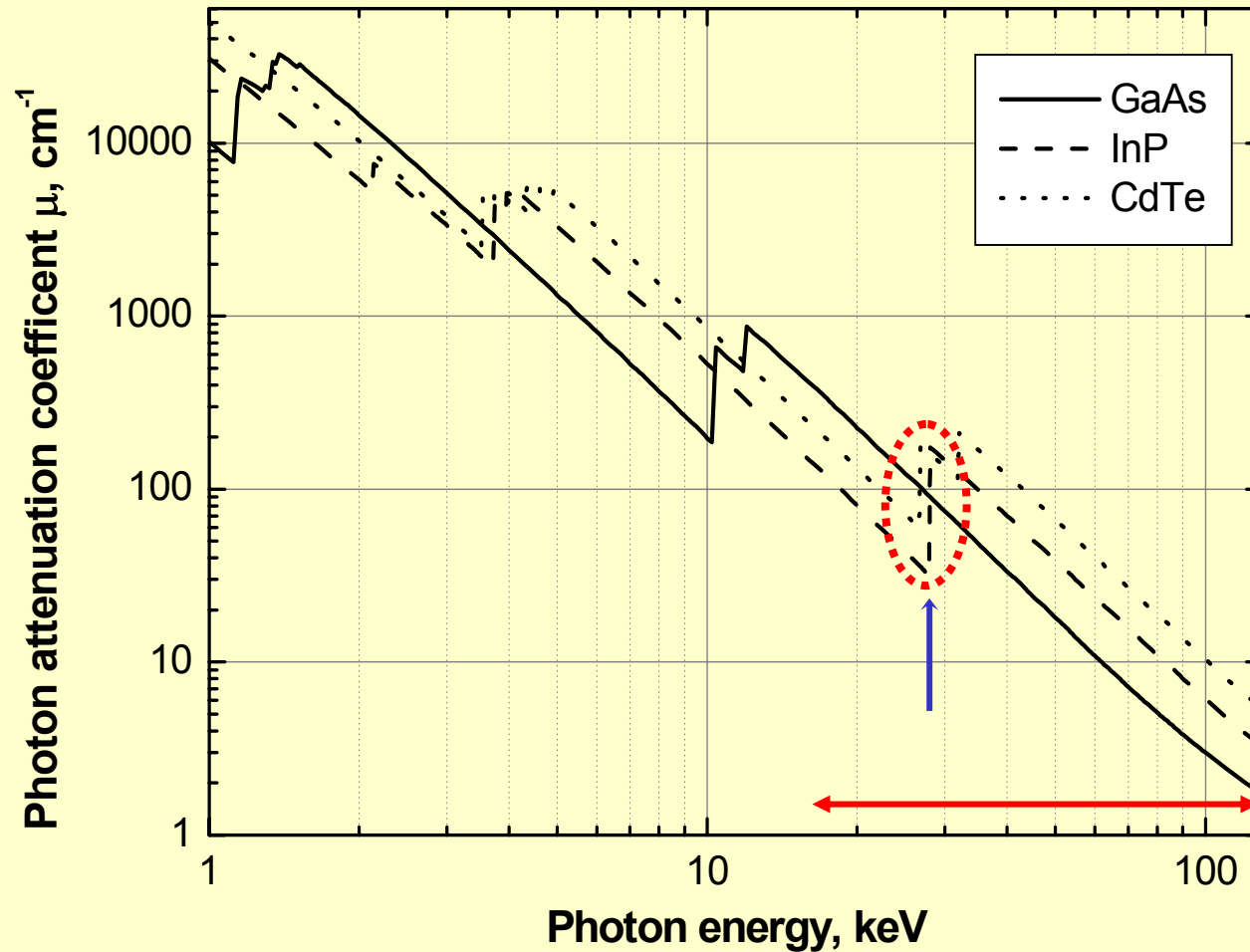
III-V: GaAs, InP, ?? GaP, GaN,...

OUT OF INTEREST: Si, Ge



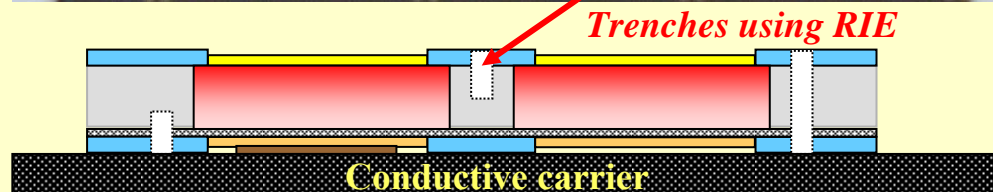
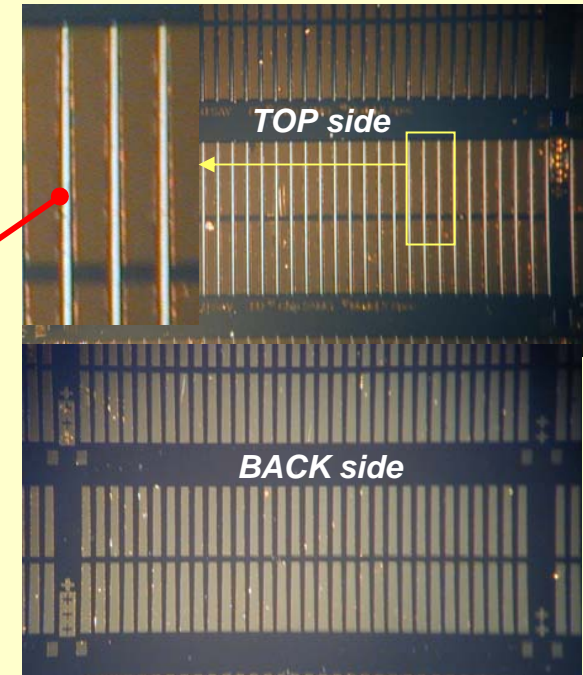
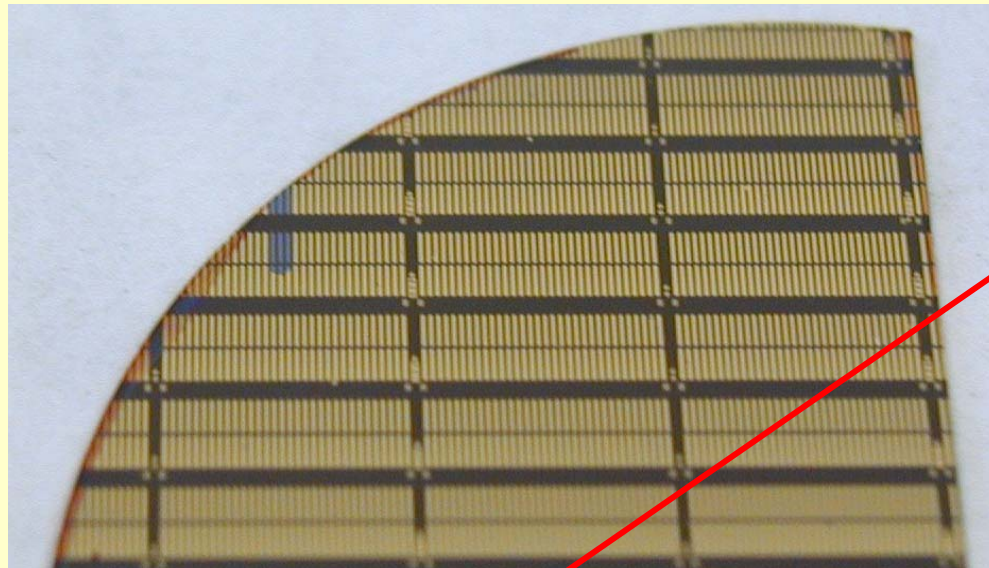
Important material aspect: Attenuation coefficient

$$A \sim Z^{4.5}$$

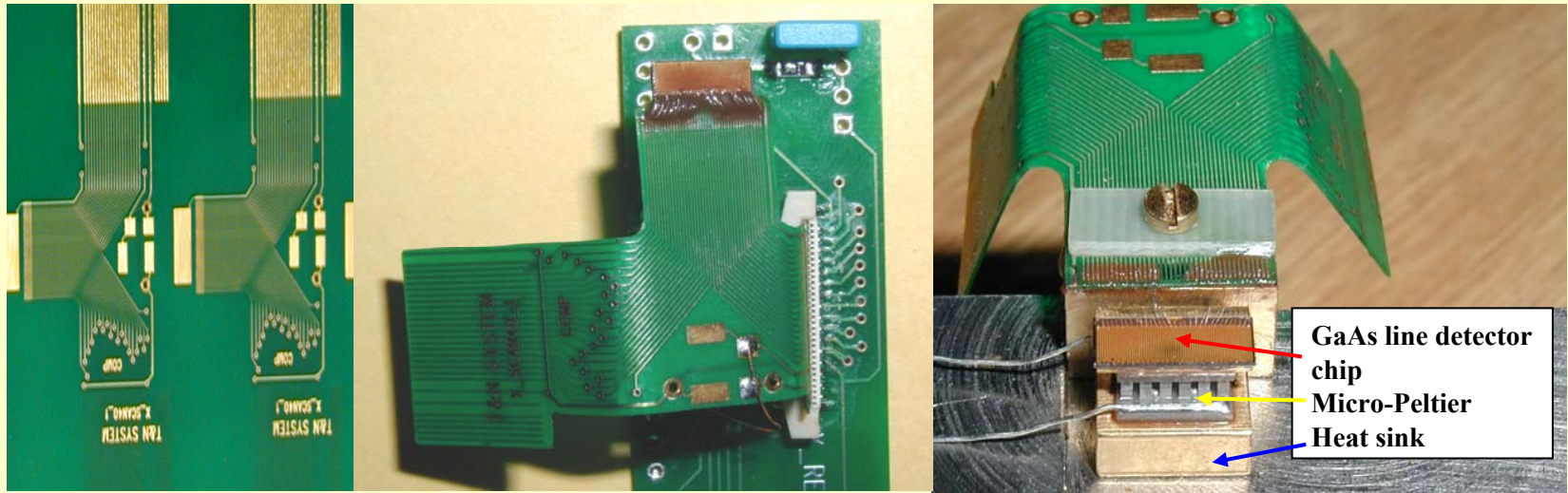


SI GaAs X- and gamma ray line detector: *New topology 2003*

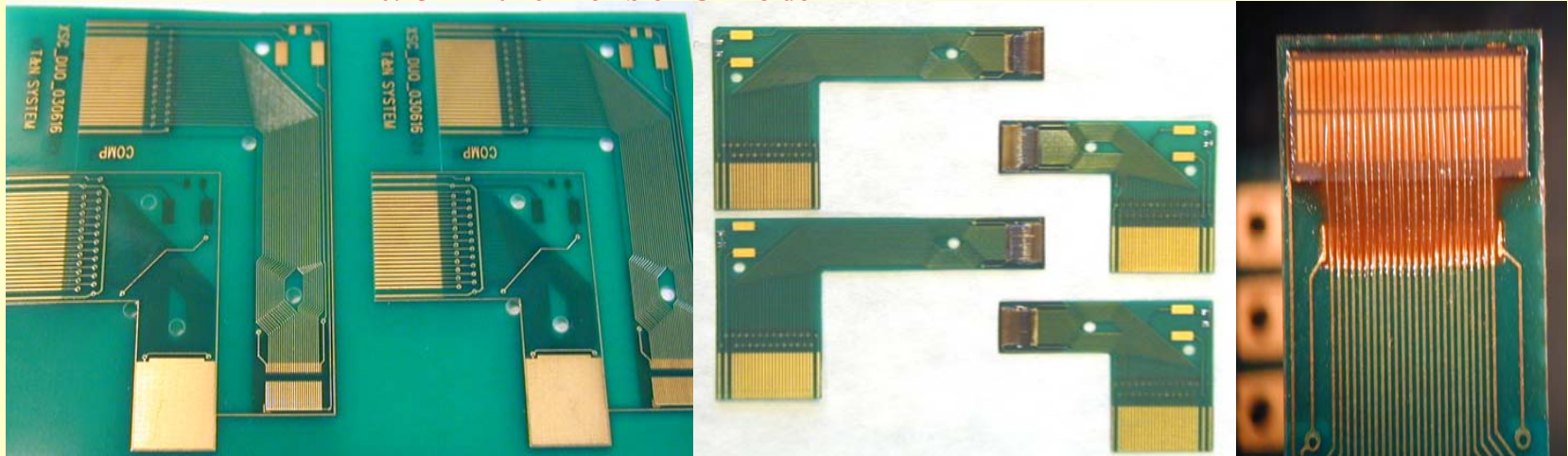
Type of developed line SI GaAs detector	Number of strips in line	Pitch, mm	Absorption length, mm	Chip dimensions, mm	Effective absorption volume of strip, mm ³	Maximal thickness of substrate base, mm
SAMO X	32 64 128	0,25 0,125/0,25* 0,125	2,5	16x3,5 16x3,5/32x3,5* 32x3,5	0,06 0,04/0,08 0,04	0,12 – 0,18
SAMO XS	32	5.9	1,25 2,5**	8x3,5	0,1 0,18	0,2 – 0,3



SI GaAs line X-ray detector chip mounted onto flexible PCB carrier: *Original concept (top), final arrangement (down)*



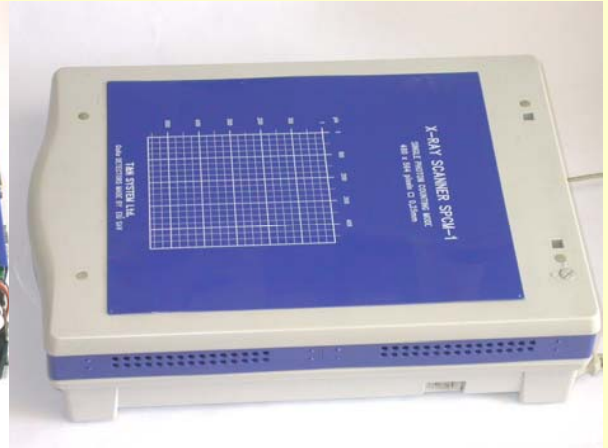
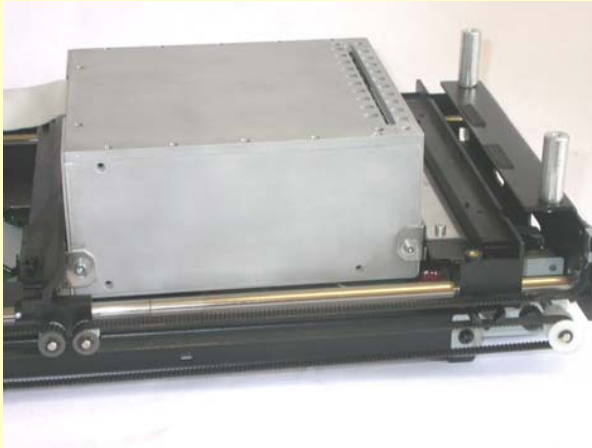
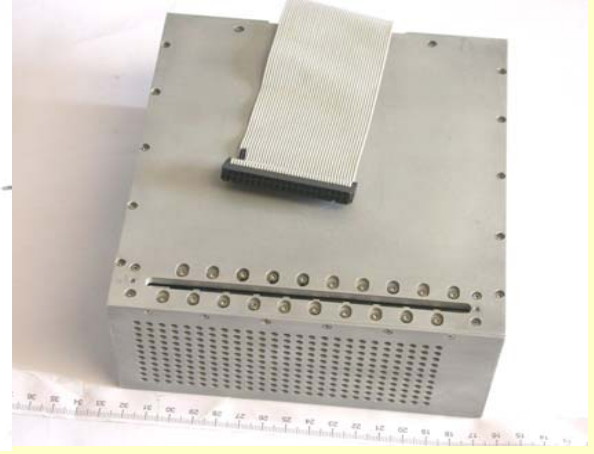
0.25 mm thick flexible PCB holder



SI GaAs DETECTOR APPLICATIONS

**SINGLE PHOTON COUNTING =
QUANTUM X-RAY SCANNER
QUANTUM X-CT: *FIRST EXAMPLE***

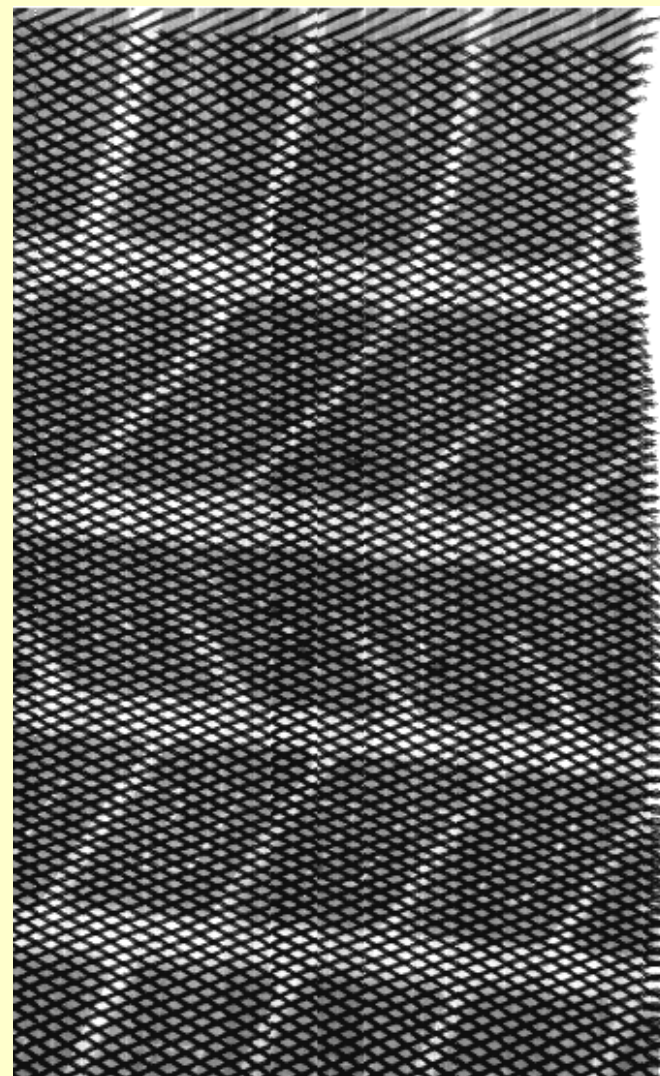
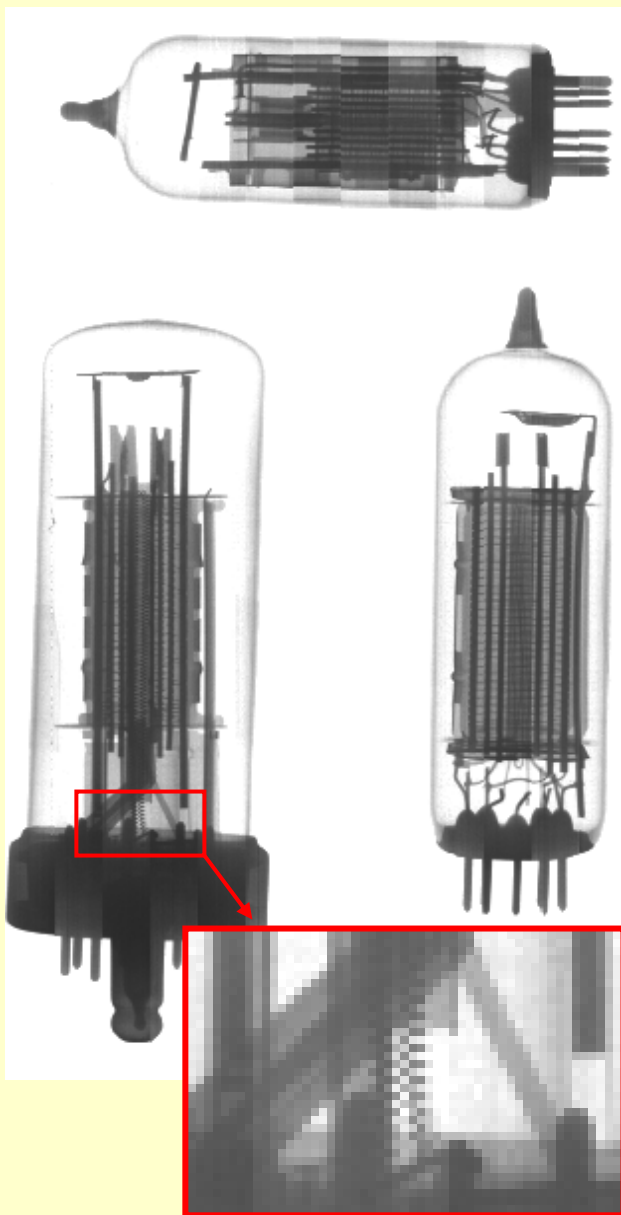
Portable digital X-ray scanner based on **SI GaAs radiation detectors:
Final set-up consists of 480 channels line, position control and communication**



Photos of various selected test objects

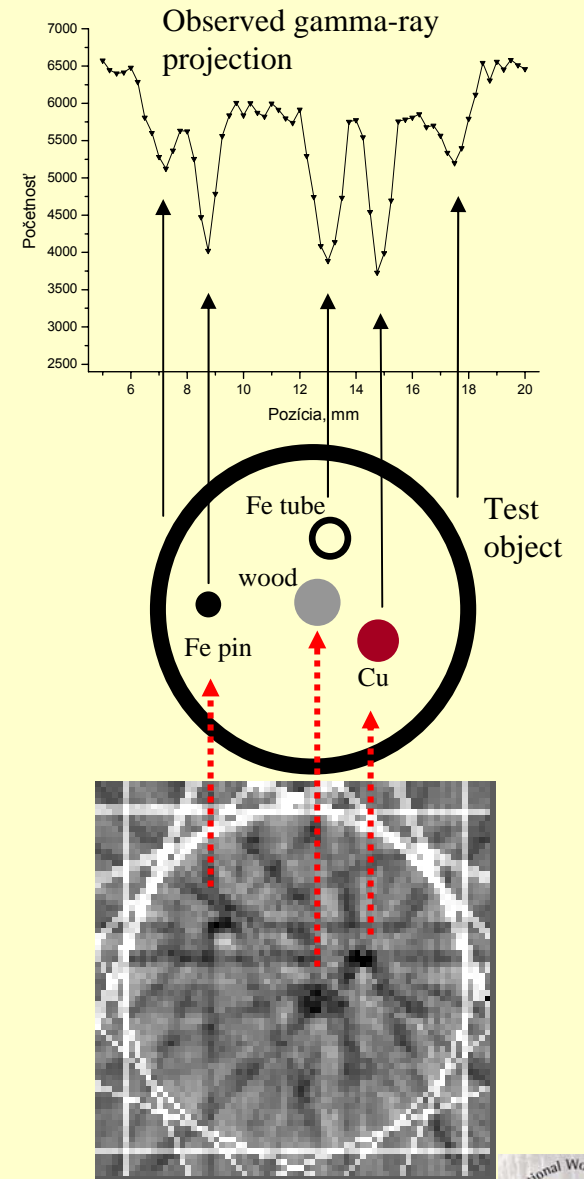


“QUANTUM” X-ray digital images of test objects

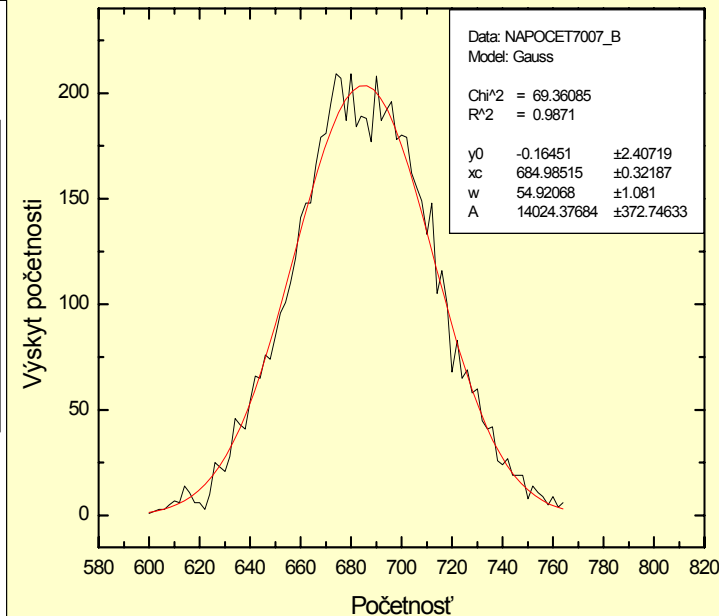
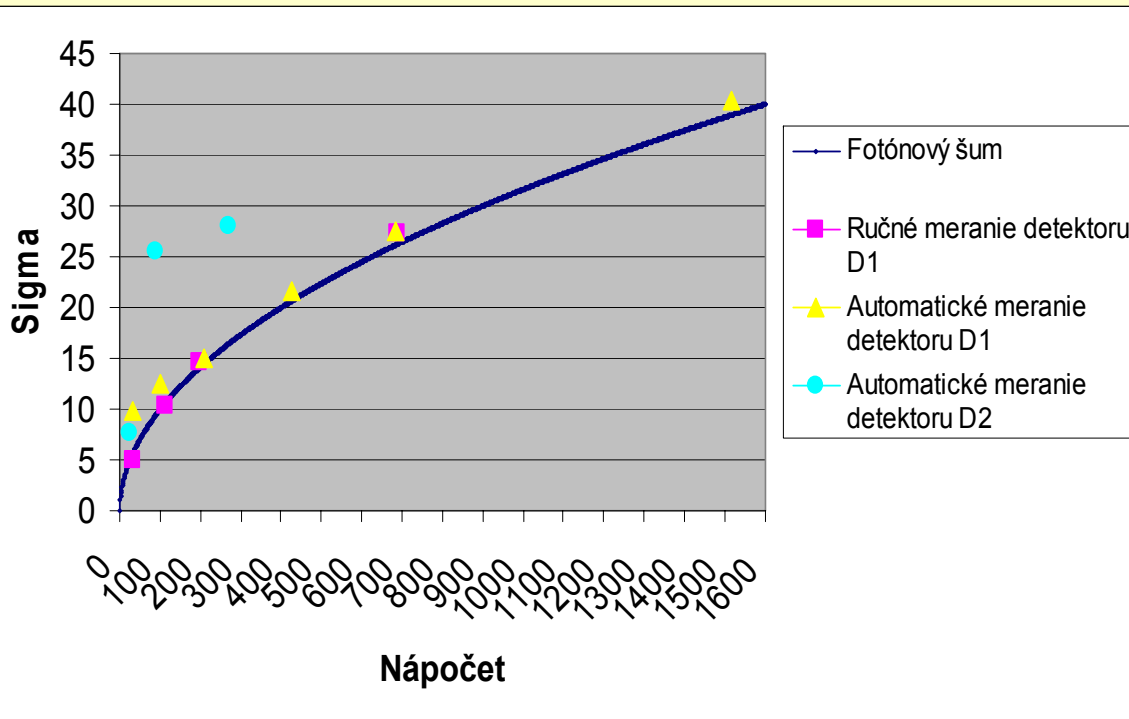


LINE STEP: 0.25 mm

Testing *X-CT platform*



GaAs detectors testing: *fluctuations in counting* – FPN



Requirements to SI GaAs detectors based on “detector grade” materials

From the point of view statistical fluctuations:

Poisson's limit: $S/N = (n)^{1/2}$

- Other goals:**
- production yield
 - stability in long-term operation
 - high homogeneity

SI GaAs

Role of key physical parameters of base materials

GDMS analysis: *SI GaAs materials*

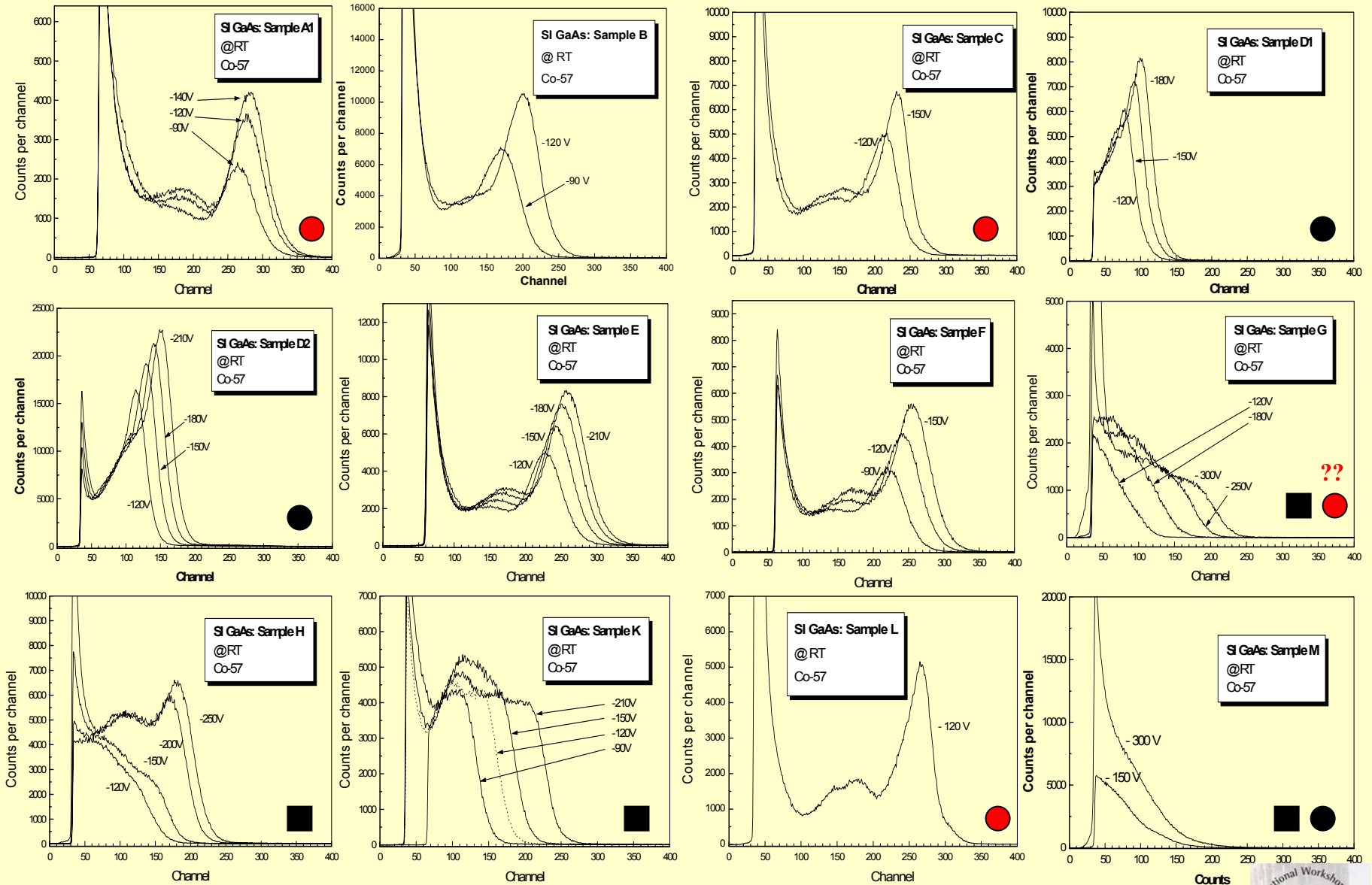
Element	Sample label											
	A1	B	C	D1	D2	E	F	G	H	K	L	M*
B	190	303	51	1041	966	271	301	71	470	n/a	20	5600
Na	<1.5	<2	<1.7	4	<2	8	3	<2	4		<1.5	3
Mg	<2	<2	<2	<2	<2	4	<1.9	<1.9	5		<1.5	<2
Al	<1	3	<1	14	<1.4	13	3	2	3		<1	9
Si	<3	11	<3	142	4	212	5	20	11		<3	445
P	<3	<3.5	4	11	<2.8	12	<3	12	20		<3	110
S	<3	21	9	7	12	25	10	10	102		<3.5	77
Cl	14	13	9	13	16	<25	12	4	13		7	11
Ti	<0.4	2	<0.4	3	<0.5	<0.5	1	<0.4	1		<0.4	<0.4
Cr	<1.2	<1.2	<1.2	<1	<1	<1	<1.2	<1.2	70		<0.9	<1.5
Fe	<0.4	1	<0.5	1.8	0.7	1.4	1.5	0.8	0.8		<0.4	8
Cu	<2.5	<3	<2.5	26	8	<3	<3	<2.5	<3		<2.5	<2.7
Total:	<447	<594	<312	<1515	<1258	<806	<576	<360	<953		<257	>6655



Following impurities were obtained in all samples under given detection limit: F<25, Li<6, Be<5, K<25, Ca<20, Mn<0.5, Ni<1.1, Zn<4, Ge<40, Se<13, Mo<1.8, Cd<0.5, In<100, Sn<4, Te<2, Sb<2, Pb<0.5, Bi<0.5. NOTICES: In the analysis there are not included C, N₂, O₂ as the background contaminants in GDMS and host atoms, Ga and As.

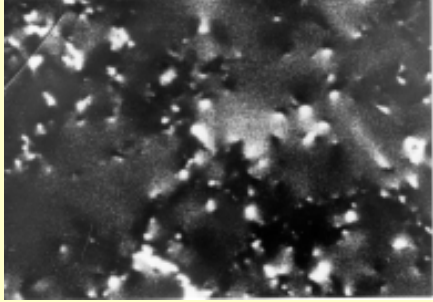

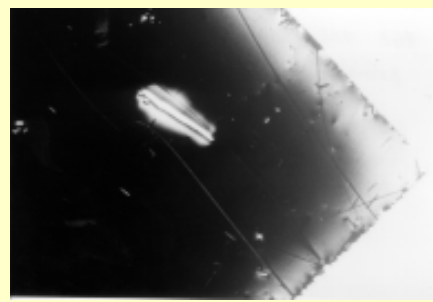

**Content of other important impurities (ppb at.) in the sample M is following: F 35, Mn 5, and Te 32.*

Detection performance: *SI GaAs detectors*



High resolution DCT and LST: *SI GaAs materials*

a) SI GaAs: LEC (B) and VGF (D1) grown materials.

Material	FWHM DD, cm^{-2}	DCT	PD, cm^{-3}	LST
B LEC ●	7.2 2×10^4		n/a	
D1 VGF ●	6.2 4×10^3		4.3×10^7	

Capacitance study: *SI GaAs detectors*

N/A

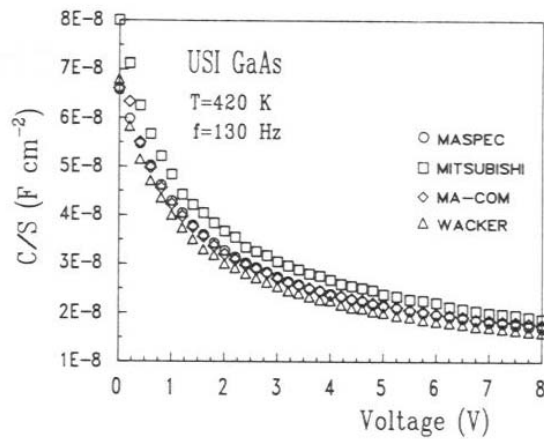


Figure 3. Measured dependences of the capacitance per unit area on voltage of the back-to-back Schottky barrier structures in undoped semi-insulating GaAs from four different manufacturers measured at 420 K and frequency 130 Hz.

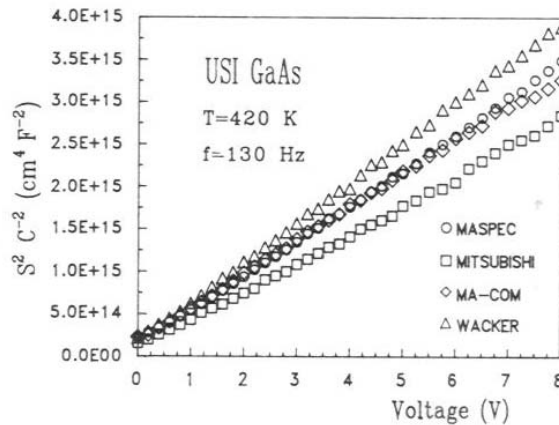
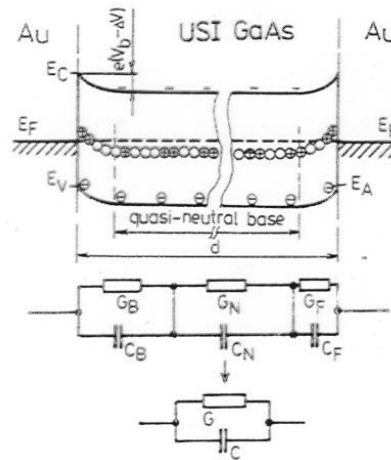


Figure 4. Calculated dependences of $S^2 C^{-2}$ on voltage of the back-to-back Schottky barrier structures in undoped semi-insulating GaAs from four different manufacturers measured at 420 K and frequency 130 Hz.

Measured capacitance	Sample label											
	A1	B1	C	D1	D2	E	F	G	H	K	L	M
T=400 K												
V _b =0	<u>780</u>	<u>1050</u>	<u>580</u>	<u>16</u>	<u>22</u>	<u>200</u>	<u>800</u>	<u>10</u>	850	220	260	<u><10</u>
f<1 kHz												



$$C_{Bif} = \frac{\Delta Q}{\Delta V_B} = S \sqrt{q \epsilon N_{ef} / 2(V_b - \Delta V + V_B)}$$

$$N_{ef} = \left(\frac{2}{q \epsilon S^2} \right) \left(\frac{\partial V_B}{\partial C_{Bif}^{-2}} \right)$$

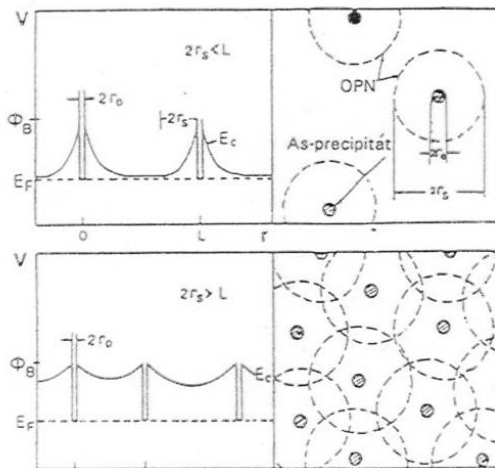
$$N_{ef} = N_{EL2} - N_{net} + N_{TD} - N_{TA}$$

$$\omega^2 C_B^2 / G_N^2 \ll 1$$

$$C_B G_N^2 / C_N G_B^2 \gg 1$$

$$G_B \ll G_N$$

F. Dubecký, et al., *Semicon. Sci. Technol.* 9 (1994) 1654



A.C. Warren, et al., *Appl. Phys. Lett.* 57 (1990) 1331

$$2r_0 = 3 \div 10 \text{ nm} \quad N_p = 10^{17} \div 10^{18} \text{ cm}^{-3}$$

P. Gall, et al., *J. Appl. Phys.* 64 (1988) 5161

$$2r_0 = 20 \div 100 \text{ nm} \quad N_p = 10^6 \div 10^8 \text{ cm}^{-3}$$

Basic electrical and material characteristics and detectors performances:

SI GaAs materials SUMMARY

Table 1. Information about bulk SI GaAs wafers and detection performances to 122 keV γ -radiation.

Sample label	Growth Method	Doping, contamination	EPD cm^{-2}	Resistivity Ωcm (RT)	Hall mobility cm^2/Vs (RT)	Detection performances (RT)		
						CCE, %	HWHM, %	P/V
A1	LEC	Non	$<6 \times 10^4$	3.9×10^6	7464 ●	79	18.5	4.2
B	LEC	Non, Ti	$<4 \times 10^4$	1.15×10^7	7227 ●	59	24	2.5
C	LEC	Non	$<4 \times 10^4$	2.44×10^7	6040	65	14	2.6
D1	VGF	Non, Cu, Fe, Ti	$<5 \times 10^3$	8.8×10^7	5400 ●	28	35	2
D2	VGF	Non, Cu, Fe	$<4 \times 10^3$	4.63×10^7	6203	43	21	2.5
E	HP LEC	Non	$<6 \times 10^5$	2.95×10^6	6940 ●	73	22.5	2.9
F	LP LEC	Non	$<2 \times 10^5$	1.06×10^7	5816	72	21.6	2.6
G	LEC	Non	$<8 \times 10^4$	2.8×10^8	5122 ●	42	no photopeak detected	
H	LEC	Cr	$<1 \times 10^5$	1.2×10^8	5770 ●	51	25	1.4
K	LEC	Non	$<2 \times 10^5$	9.65×10^6	7517 ● ??	57	no photopeak detected	
L	LEC	Non	$<6 \times 10^4$	2.6×10^7	6915 ●	72	12.5	3.8
M	LEC	Non	$<8 \times 10^5$	1.4×10^8	4830 ●	32	no photopeak detected	

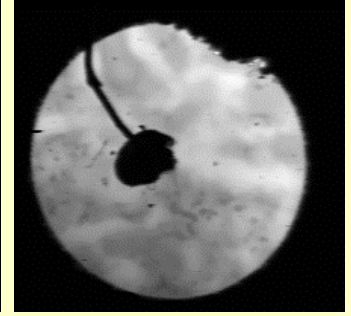
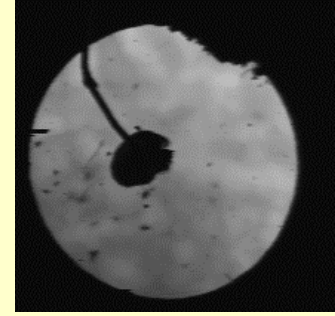
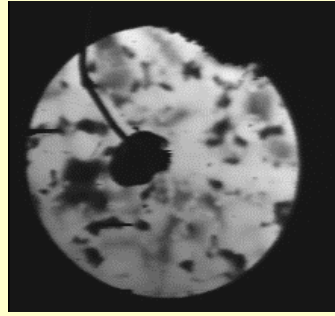
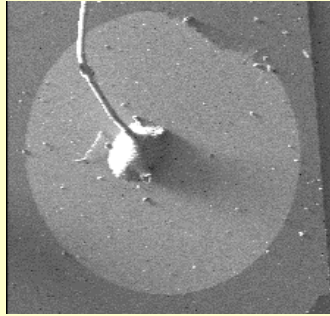
EBIC: *SI GaAs*

SE

Bias voltage: 0

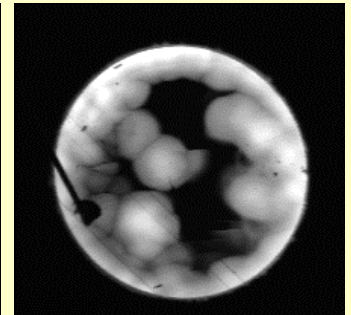
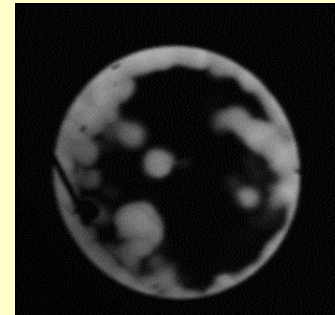
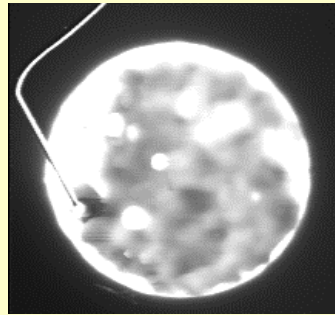
-30 V

-60 V



E: M/A COM
HP LEC SI GaAs

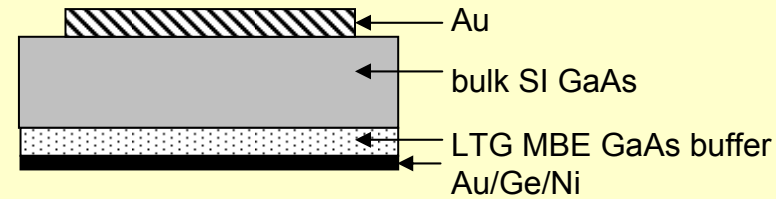
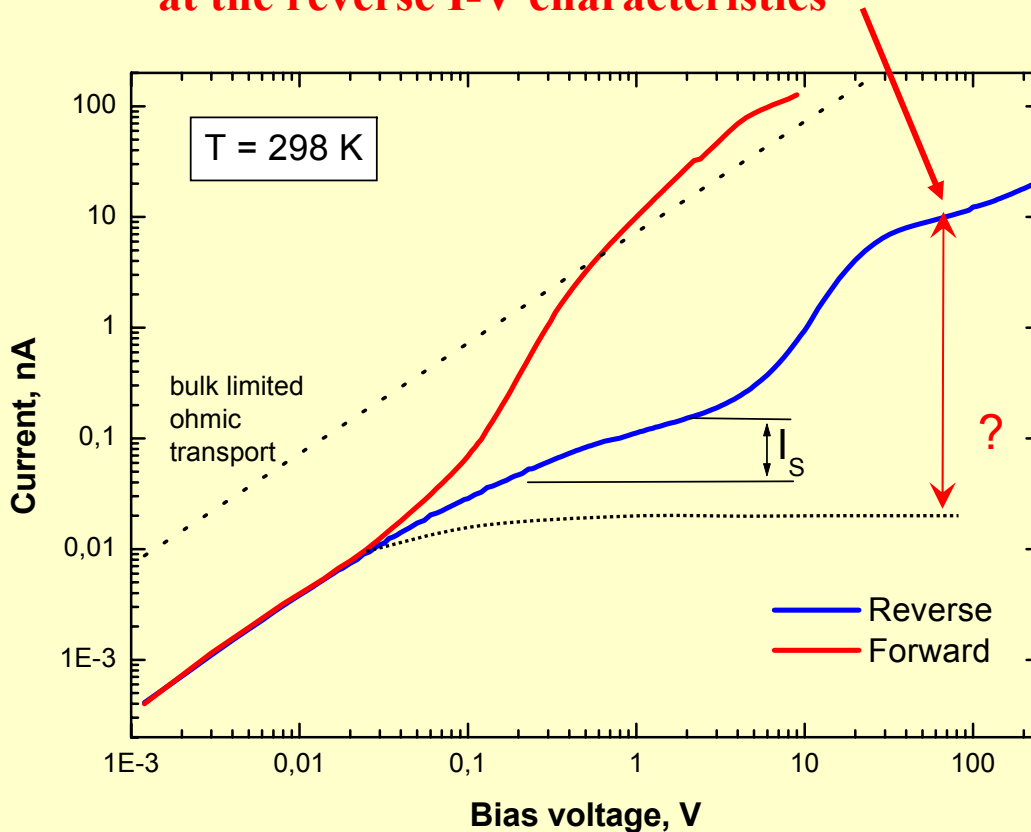
F: M/A COM
LP LEC SI GaAs



Detector contact: 2 mm diameter
Base thickness: 200 μ m

I-V characteristic of **SI GaAs** detector with the Schottky barrier

?? Explanation of the second current saturation region observed at the reverse I-V characteristics



Thermionic emission
current via
Schottky barrier

$$I = I_S \left[e^{\frac{q(V - IR_S)}{nkT}} - 1 \right]$$

Saturation current

$$I_S = AA^{**} T^2 e^{-\frac{q\phi_B}{kT}}$$

I-V characteristics of SI GaAs detectors with the Schottky barrier (2 mm diameter)

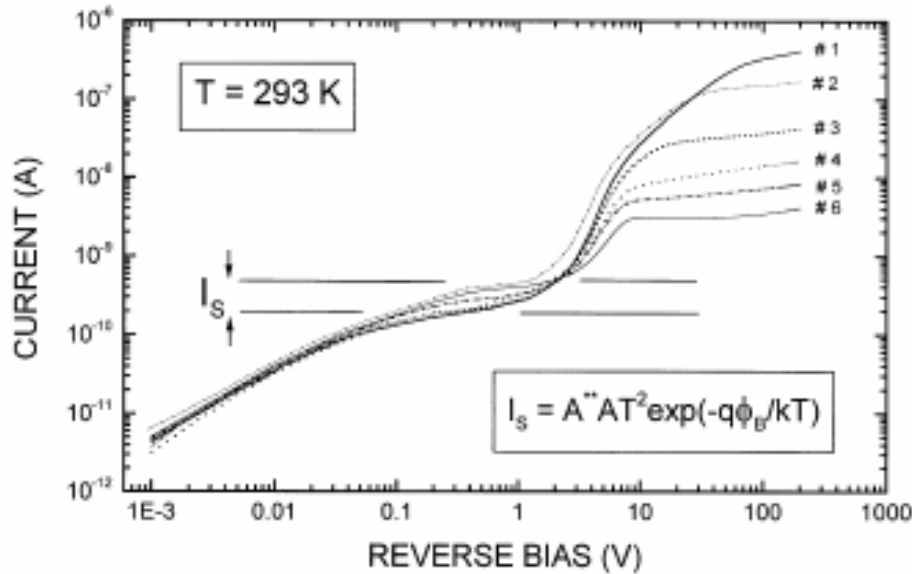


Fig. 2. A detailed reverse current behaviour from low voltages, 1×10^{-3} V, to 200 V, with the saturation current, I_s , range indicated.

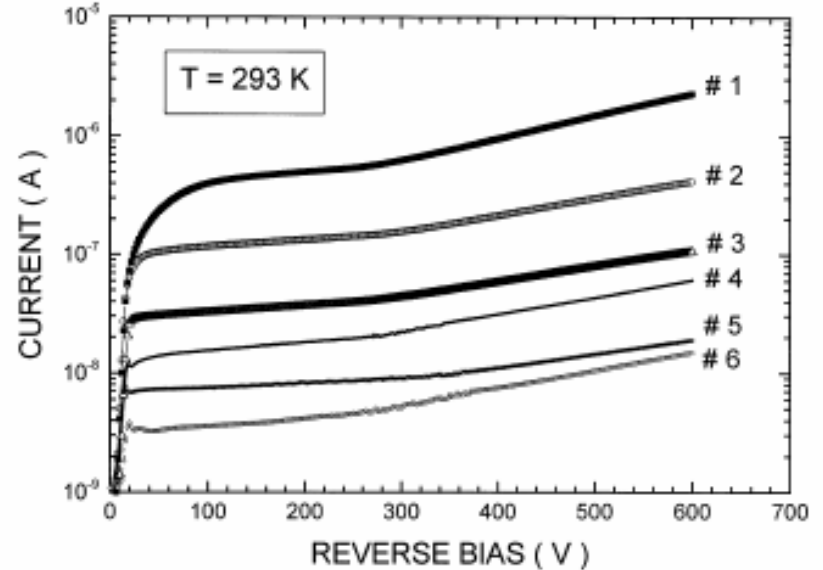
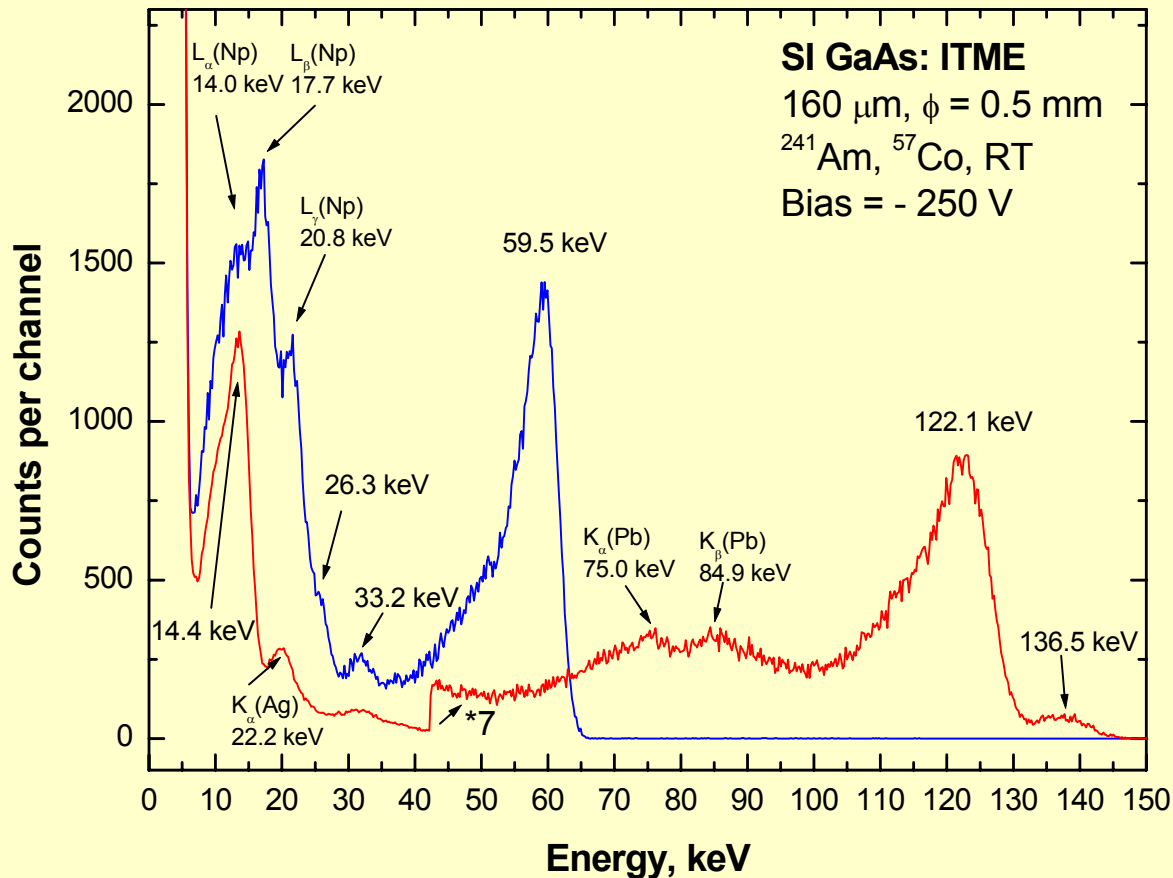


Fig. 1. Room-temperature $I-V$ characteristics versus reverse bias voltage for SI LEC GaAs detectors at different acceptor dopant concentrations, N_a , as reported in Table 1.

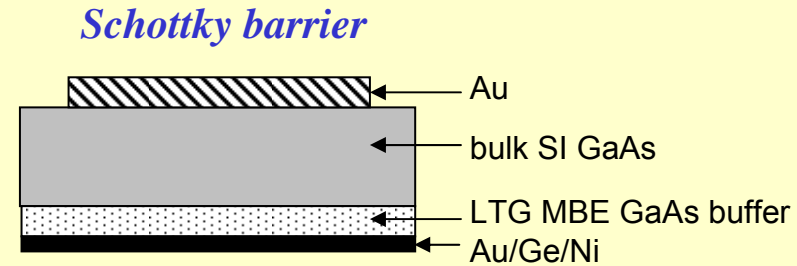
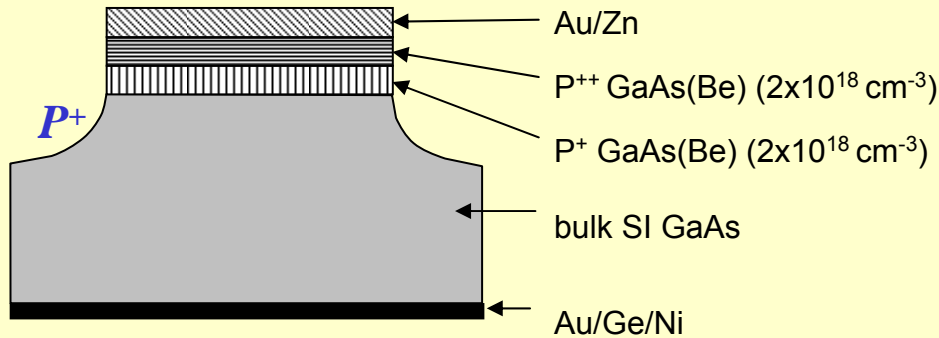
Baldini, R., et al., NIM A 449 (2000) 268

Pulse-height spectra of ^{241}Am and ^{57}Co detected by “dedicated” SI GaAs PAD detector

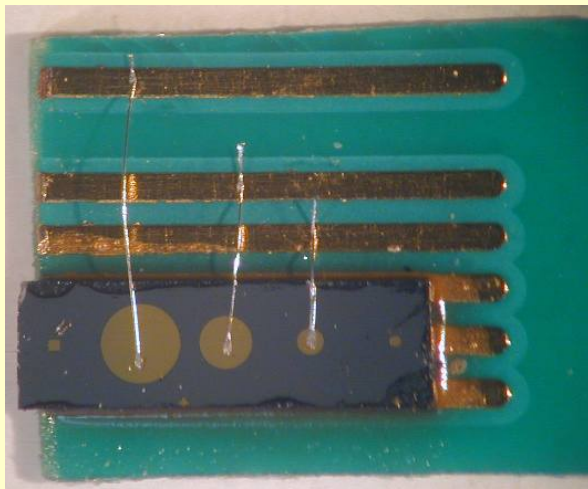


B. Zat'ko at al.: Nucl. Instr. Meth. A (2004)

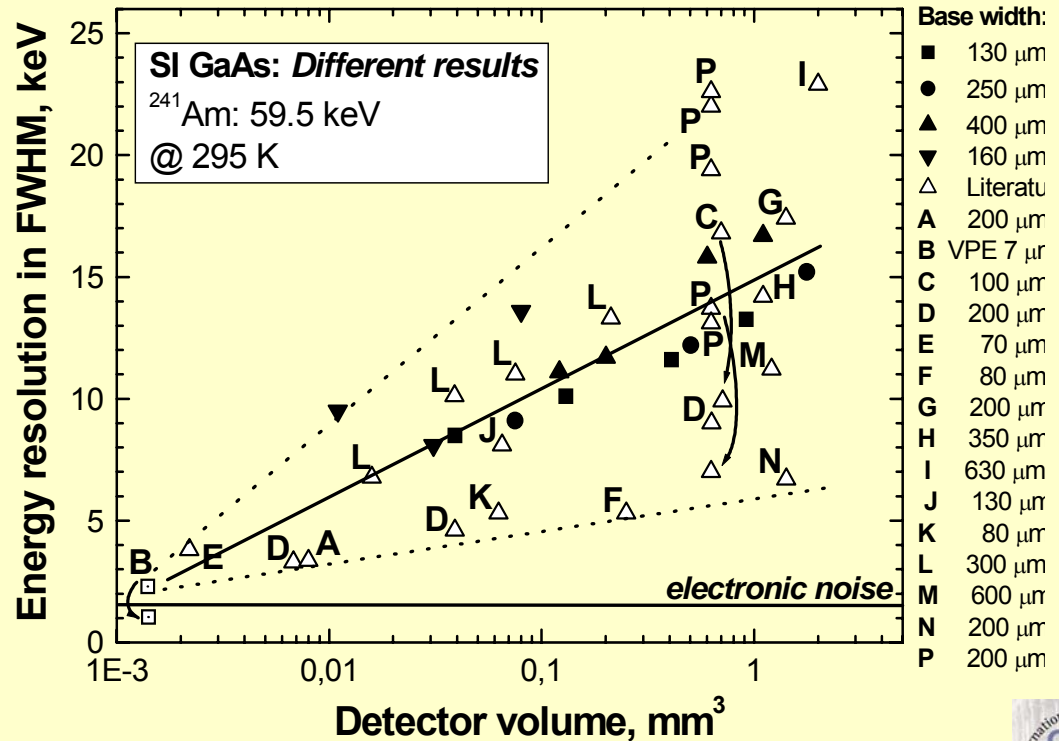
SI GaAs detectors structure



Optimization of the ohmic and blocking SI GaAs detector contacts



Zat'ko, B., et al., NIM A531 (2004) 111



Conclusions

- **Bulk SI GaAs:** Radiation detector-grade material is available on the market!
- **Key material characteristics:** - preferable VGF, low dislocation density
- high chemical purity (GDMS)
- RT Hall mobility > 6500 cm²/Vs
- RT resistivity (0.8 – 3)e7 ohm cm
- **Following material evaluation tools:** X-ray topography, LST, PL, ...
- **Detector evaluation tools:** I-V, C-V, EBIC, pulse height spectra,...
- **Detector electrodes:** Must be optimized for required performance
- **Schottky back-to-back electrode technology:** Potential improvement must be investigated in more details!!
- **PERSPECTIVE APPLICATIONS:** *Quantum X-RAY IMAGING, Quantum X-CT,...*
- **BASIC & SPACE RESEARCH:** *PLASMA DIAGNOSTIC IN NUCLEAR FUSSION*

THANK YOU
FOR YOUR ATTENTION!!!